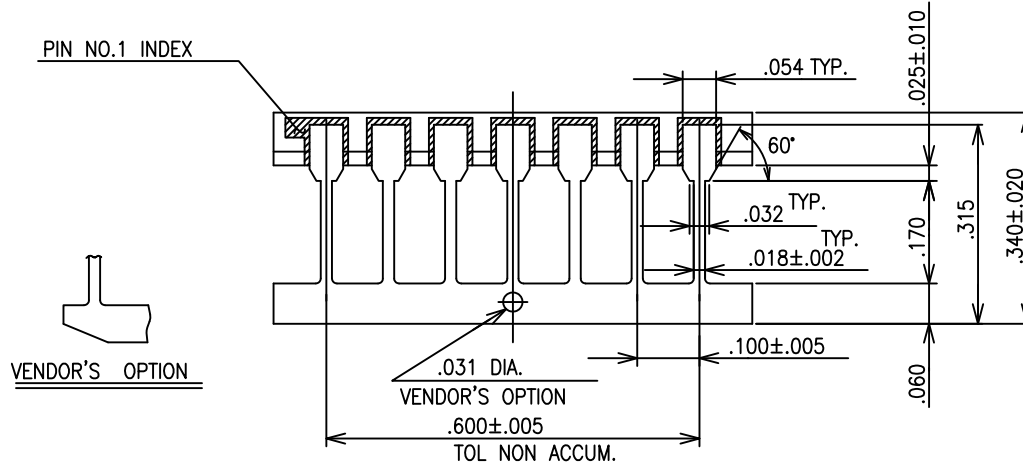
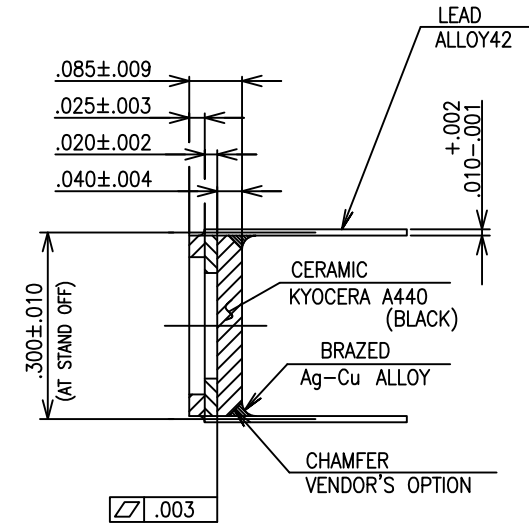
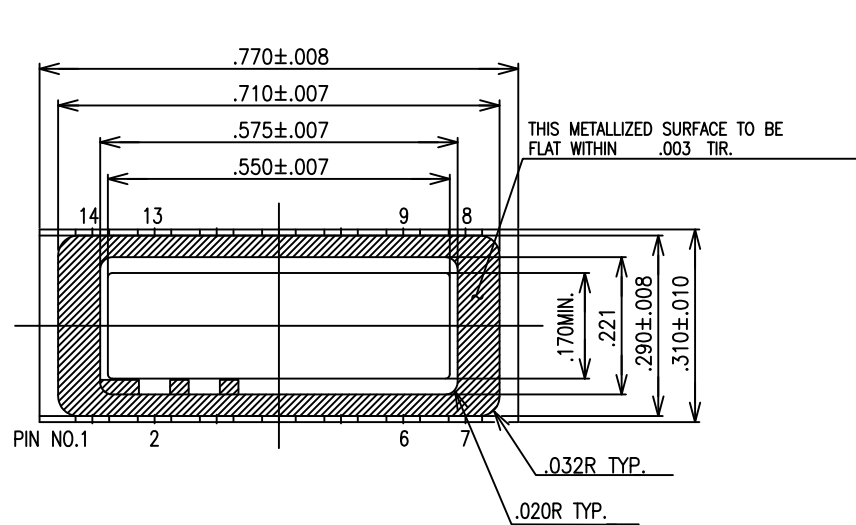


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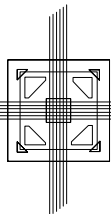


**NOTES:**

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE NOT METALLIZED.
4. SEAL RING TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE : 0.25 OHM MAX.

SB014K095-1 S=0  
D=N

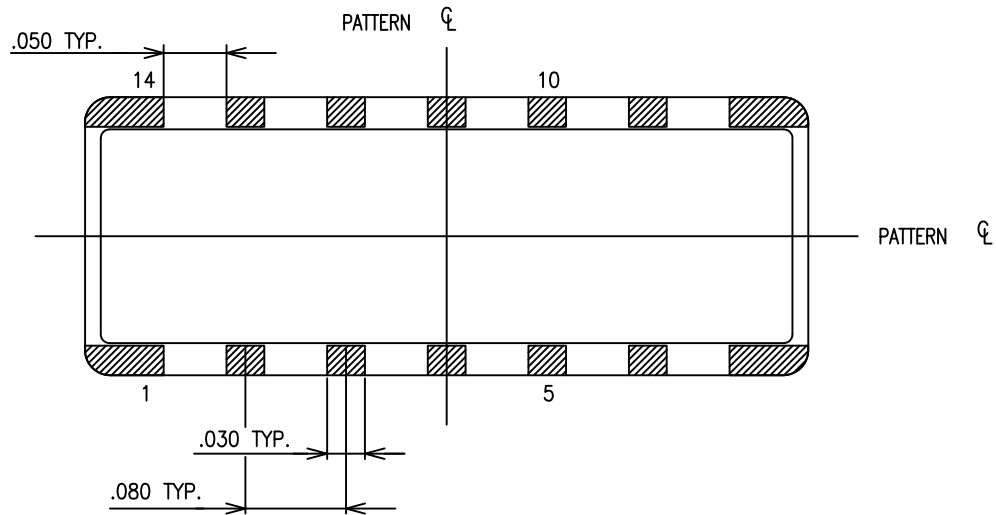
MODIFICATION						NAME 14 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN M.M	CHECKED K.M	APPROVED	DATE FEB.28.'80
						SCALE 5/1	MATERIAL AS INDICATED				
	REDRAWN(CONVERTED CAD DATA) CHANGED	APR.9.'96	Y.M	K.N/K.I	T.A		KYOCERA CORPORATION KYOTO JAPAN			DRAWING NO. KD-80095-A	SHEET 1/2



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BONDING PATTERN

MODIFICATION					NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
					14 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	Y.M	K.N/K.I	K.M	APR.9.'96
					SCALE 10 / 1	MATERIAL				
						THIRD ANGLE PROJECTION				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-80095-A		SHEET 2/2

